

**Product/ Process Change Notification** 

Product/ Process Change Notification					
1. PCN No.:		QPCN13004-1			
2. Subject:		Schottky FE (Front End) wafer production location and wafer technology change			
3. To:		All involved customers			
4. Issued by:		HQ (Headquarter) QRA. Owen Wang			
5. Issue date:		27-Mar-2013			
6. Proposed first ship date for change:		27-Jun-2013			
7. Affected Product Identification					
See attached detailed Part-No. list.					
8. Change Description : (OLD	Vs. NEW Com	nparison)			
Old:		New:			
> I-Lan TSC own wafer fab loca	ted in Taiwan.	➤ I-Lan fab shut down			
> Technology (see attached comparison report)		<ul> <li>Use sub-con wafer fab located in China.</li> <li>Technology (see attached comparison report)</li> </ul>			
9. Reason for Change:					
Keep competitive prices and continuous product quality improvement strategy  10. Anticipated Impact: (form, fit, function, quality or reliability)					
1. Product outline: No chang		le			
		attached comparison report			
3. Electrical specifications: No change					
4. Reliability performance: No change 5. Data sheet: No change No					
6. Packing code (order code): No chang					
7. Identification/Traceability: By date of					
11. Qualification plan/result:					
Refer to					
PPAP		Available on demand			
Comparison report	Available on d	railable on demand			
12. Sample availability Date:		27-Mar-2013			
13. Tentative implementation date:		27-Mar-2013			
14. Remarks					
15. Customer feedback required latest: (should we receive no feedback; the change will be deemed as accepted!)		3-May-2013			
16. Approved by:		Quayer Chen			



## **Product/ Process Change Notification** Customer Approval Form\_QPCN13004-1

(Please tick the field what is valid for you!)						
We agree with this proposed change and its schedule.						
	We have object	tions				
	We need more					
We need sample:						
Con	npany:					
Nan	<u>'</u>					
	lress:					
Sigi	nature:		Date:			